



Abstract

A heat sink (2) for electronic components (1) comprises: a base portion (3) fitted with means (4) for coupling with a fixed support plane (5) of an apparatus; a plane surface (6), positioned in proximity to the base portion (3), in contact with a corresponding surface (7) of the electronic component (1), and an additional heat dissipation portion (8) comprising a prolongation (9) of the base portion (3) from which extend a plurality of fins (10); an elastically yielding element (11) acts between the heat sink (2) and the electronic component (1) to obtain a stable positioning of the surface (7) of the component itself to the related plane surface (6) of the heat sink (2); a pair of fins (10a, 10b), contiguous to each other, presents a respective inner wall (12, 13), such walls being opposite one to the other and so shaped as to define a compartment (14) for stably housing a portion (15) of the elastically yielding element (11). (FIGURE 1)